

IN THE SPECIFICATION

Please amend the Title of the Invention as follows:

~~FREESTANDING REACTIVE MULTILAYER FOILS~~

**METHOD OF CONNECTING SEMICONDUCTOR
OR MICROELECTRONIC DEVICE TO A SUBSTRATE**

At Page 1 of the specification, please move the entire section entitled **“Government Interest”** so that it appears immediately after the section entitled **“Cross Reference to Related Applications”**.

At Page 1 of the specification, please amend the section entitled **“Cross Reference to Related Applications”** to read as follows:

~~This application claims the benefit of United States Provisional Application~~
This application is a divisional of prior United States Application Serial No. 09/846,486
filed on May 1, 2001, which is a non-provisional application that claims the benefit of U.S.
Provisional Application Serial No. 60/201,292, filed by the present applicants on May 2,
2000 and entitled “Reactive Multilayer Foils”. It Application No. 09/846,486 is related to
U.S. Application Serial No. 09/846,447, now U.S. Patent No. 6,534,194, filed by M.E.
~~Reiss et al. concurrently herewith and entitled “Method of Making Reactive Multilayer~~
~~Foil and Resulting Product” May 1, 2001 and U.S. Application Serial No. 09/846,422, filed~~
~~by T.P. Weihs et al. concurrently herewith and entitled “Reactive Multilayer Structures For~~
~~Ease of Processing and Enhanced Ductility” May 1, 2001. These three related applications~~
All of the documents cited in this section are incorporated herein by reference.